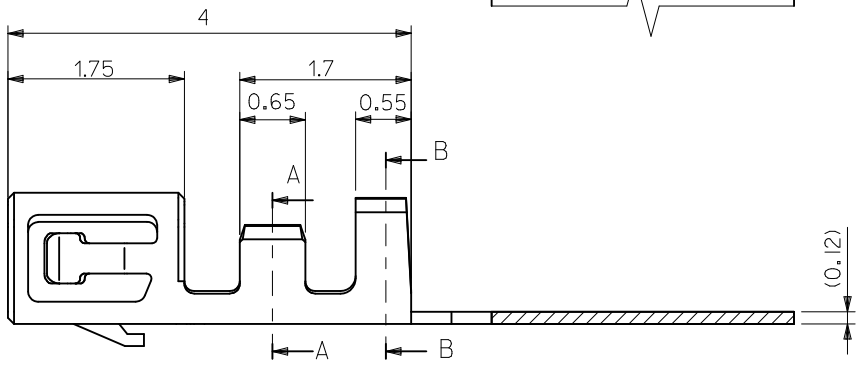
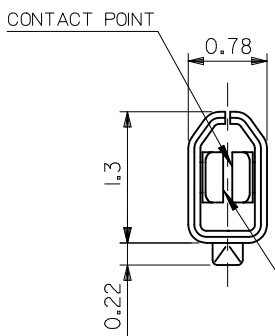
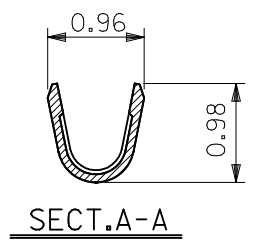
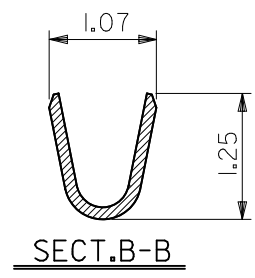
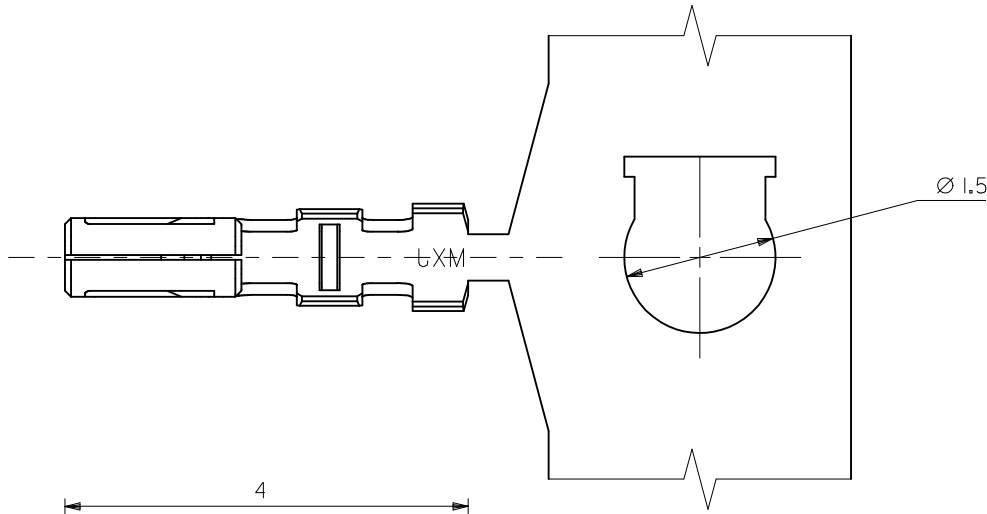


10 9 8 7 6 5 4 3 2 1

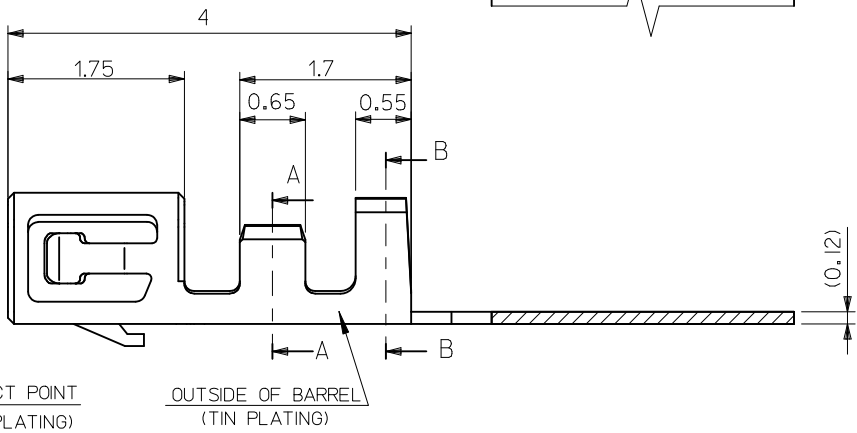
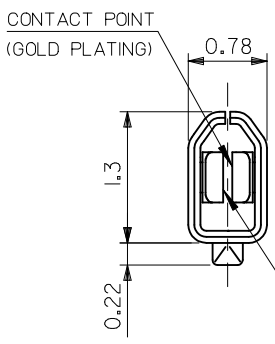
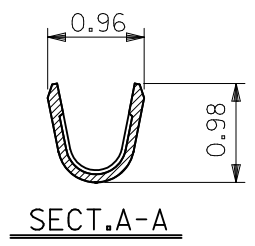
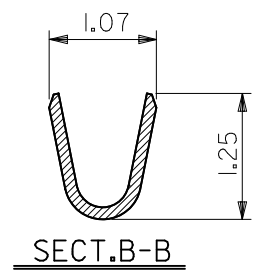
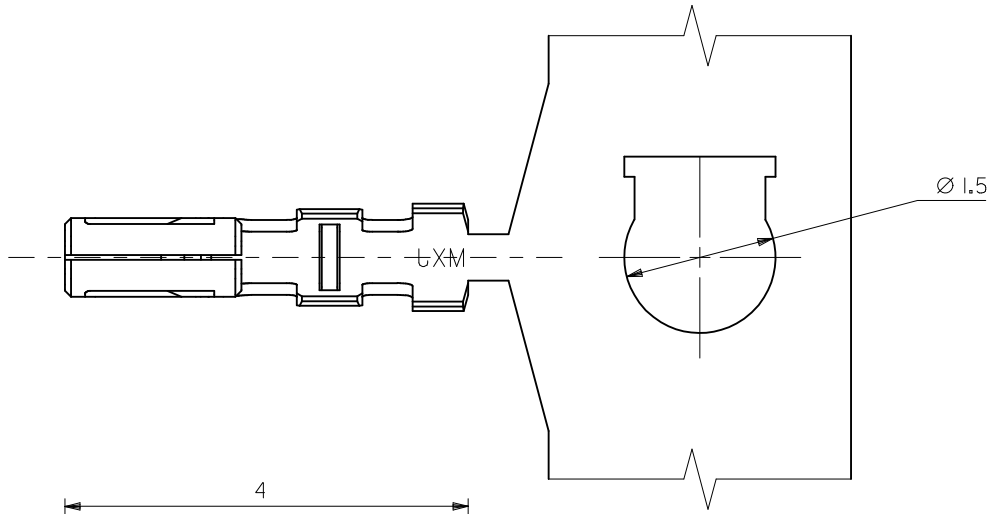


NOTES.

- 適合ハウジング: 501189-****
APPLICABLE HOUSING : 501189-****
- メッキ仕様 (前メッキ)
PLATING (PRE-PLATING)
接点部金メッキ: 0.1μm MIN.
CONTACT AREA GOLD PLATING
下地ニッケルメッキ: 1.0μm MIN.
UNDER PLATING NICKEL PLATING
- 本製品は 501193 の部分金メッキ品である。
THIS PRODUCT IS A PRODUCT THAT GAVE 501193
A PARTIAL GOLD PLATE.

| | |
|--------------|--------------|
| 501193-2100 | バラ状 LOOSE |
| 501193-2000 | 連鎖状 CHAIN |
| MATERIAL NO. | 端子形状 FORM |

| | | | | | | | | | |
|------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------|--------------------------------------------|---------------------------------------------------------------|---------------------------|--|--|
| MATERIAL リン青銅 下地ニッケル、部分金メッキ品 PHOSPHOR BRONZE t=0.12 PRE-GOLD PLATING PRE-UNDER NICKEL PLATING | REVISED EC NO: J2010-1758 DRWN:HKOBAYASHI 2010/03/02 CHKD:SSAT003 2010/03/02 APPR:NUKITA 2010/03/02 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 20:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 | DRAWN BY M. NABEI DATE '07/11/13 | CHECKED BY K. TOYODA DATE '07/11/13 | APPROVED BY NUKITA DATE '07/11/13 | TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL | | | |
| | | ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-501193-002 | SHEET NO. 1 OF 1 | MOLEX INCORPORATED | | | |
| | | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | |



- NOTES.
1. 適合ハウジング: 501189-****
APPLICABLE HOUSING : 501189-****
 2. メッキ仕様 (前メッキ)
PLATING (PRE-PLATING)
接点部金メッキ: 0.1μm MIN.
CONTACT AREA GOLD PLATING
バレル外面 錫メッキ: 0.9μm MIN.
OUTSIDE OF BARREL TIN PLATING
下地ニッケルメッキ: 1.0μm MIN.
UNDER PLATING NICKEL PLATING
 3. 本製品はコンタクト部 金メッキ品である。
THIS PRODUCT IS GOLD PLATING FOR CONTACT POINT.
 4. 本製品はバレル外面 錫メッキ品である。
THIS PRODUCT IS TIN PLATING OUTSIDE A BARREL.
 5. ELV AND RoHS COMPLIANT.

| | |
|--------------|--------------|
| 501193-3100 | バラ状 LOOSE |
| 501193-3000 | 連鎖状 CHAIN |
| MATERIAL NO. | 端子形状 FORM |

| | | | | | | | | |
|--------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------|---------------------------|-----------------------------------|---------------------------------------------------------------------------------|-------------------------------|---------------------------|--|
| MATERIAL リン青銅 下地ニッケル、部分金メッキ、錫メッキ品 PHOSPHOR BRONZE t=0.12 SELECTIVE GOLD PLATING SELECTIVE TIN PLATING UNDER NICKEL PLATING | RELEASED EC NO: J2011-0328 DRWN:TKON 2010/09/01 CHKD: 2010/09/02 APPR:NUKITA 2010/09/02 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 20:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | |
| | | 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 | DRAWN BY TKON | DATE 2010/09/01 | TITLE 1.0 WIRE TO BOARD CONN. CRIMP REC TERMINAL | | | |
| | | ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | APPROVED BY NUKITA | DATE 2010/09/02 | MOLEX INCORPORATED | | | |
| | | SEE NOTE WIRE RANGE AWG#28-32 INS. RANGE ø 0.4-0.8 | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-501193-003 | SHEET NO. 1 OF 1 | | | |